

PHOTOSENSITIVE RESIN COMPOSITION, CURED FILM, ELECTRONIC
COMPONENT, ANTENNA ELEMENT, SEMICONDUCTOR PACKAGE, AND
COMPOUND

ABSTRACT

The purpose of the present invention is to provide a photosensitive resin composition and compound having a low dissipation factor when made into a cured film.

The present invention is a photosensitive resin composition containing (A) a polyfunctional monomer, (B) a binder resin, and (C) a photopolymerization initiator, the (A) polyfunctional monomer containing a compound represented by expression (1) and/or a compound represented by expression (2), and the (B) binder resin containing one or more substances selected from the group consisting of a polyimide, a polyimide precursor, a polybenzoxazole, a polybenzoxazole precursor, a polyamide, a copolymer thereof, a polyurea, a polyester, a polysiloxane, an acrylic resin, a phenol resin and a benzocyclobutene resin, and a maleic acid resin and a cycloolefin polymer.